Special Issue

Additive Manufacturing – Process Optimisation

Message from the Guest Editor

The objective of this Special Issue is to provide a forum for researchers and practitioners to exchange their latest achievements and to identify critical issues and challenges in AM process optimisation. "Optimisation" can be based on the part's *density*, *mechanical properties*, *dimensional accuracy*, *chemical composition*, or *process sustainability*.

Guest Editor

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Deadline for manuscript submissions

closed (31 March 2024)



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Message from the Editor-in-Chief

Designs (ISSN 2411-9660) is a peer-reviewed and open access journal which provides a unifying research framework for a wide range of engineering designs of disciplines and industrial applications, including mechanical engineering, electrical engineering, civil engineering, mechatronics, aerospace engineering, bioengineering, energy engineering, industrial engineering and manufacturing systems are of interest. We would like to invite you to contribute to the journal by sending us your high quality research papers. We would be pleased to welcome you as one of our authors.

Editor-in-Chief

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